



24TH ANNUAL
COMPONENTS
FOR MILITARY &
SPACE ELECTRONICS
VIRTUAL CONFERENCE



APRIL 19-23

- Keynote talks by industry leaders
- Over 35 technical presentations by industry experts with Q&A
- Focused panel discussion on topics such as; use of alternate grade parts for mil and space
- Vendor presentations and virtual exhibits
- Cutting edge tutorials

LEARN MORE AT WWW.TJGREENLLC.COM/CMSE

 **Advanced
International
Technology**

OVERVIEW OF PRODUCT & SERVICES AT CMSE

From Design to Physical Device

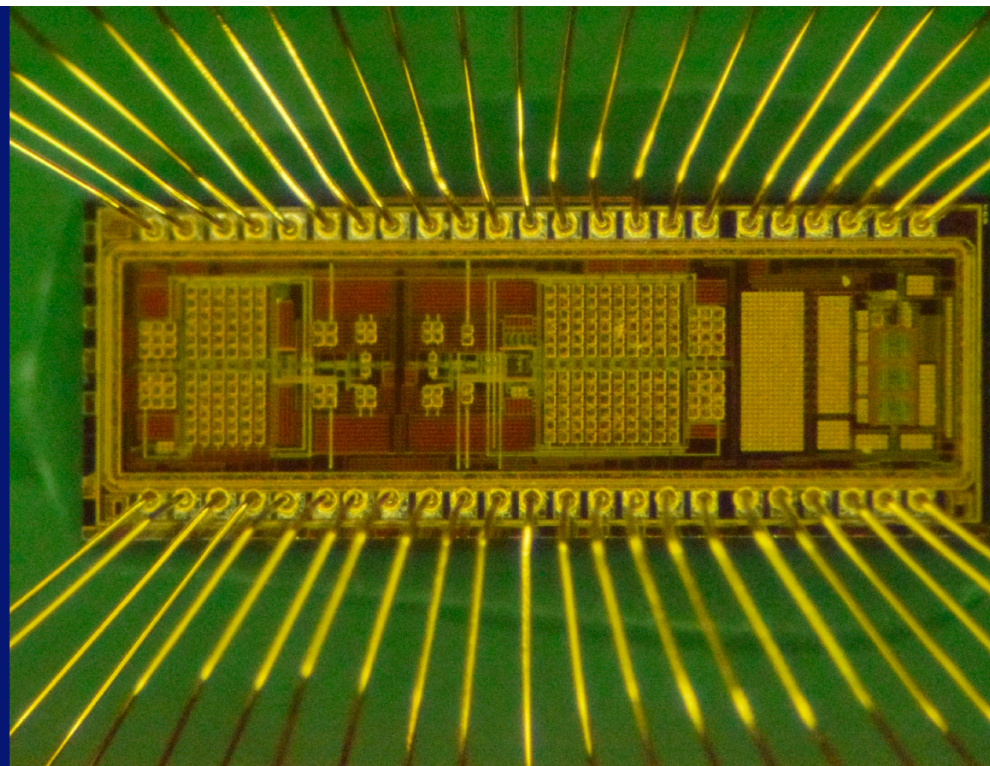
Advanced International Technology provides specialized back-end wafer processing, micro assembly and fabrication services. Prototyping and small to medium builds are our specialty.

APRIL 19, 2021



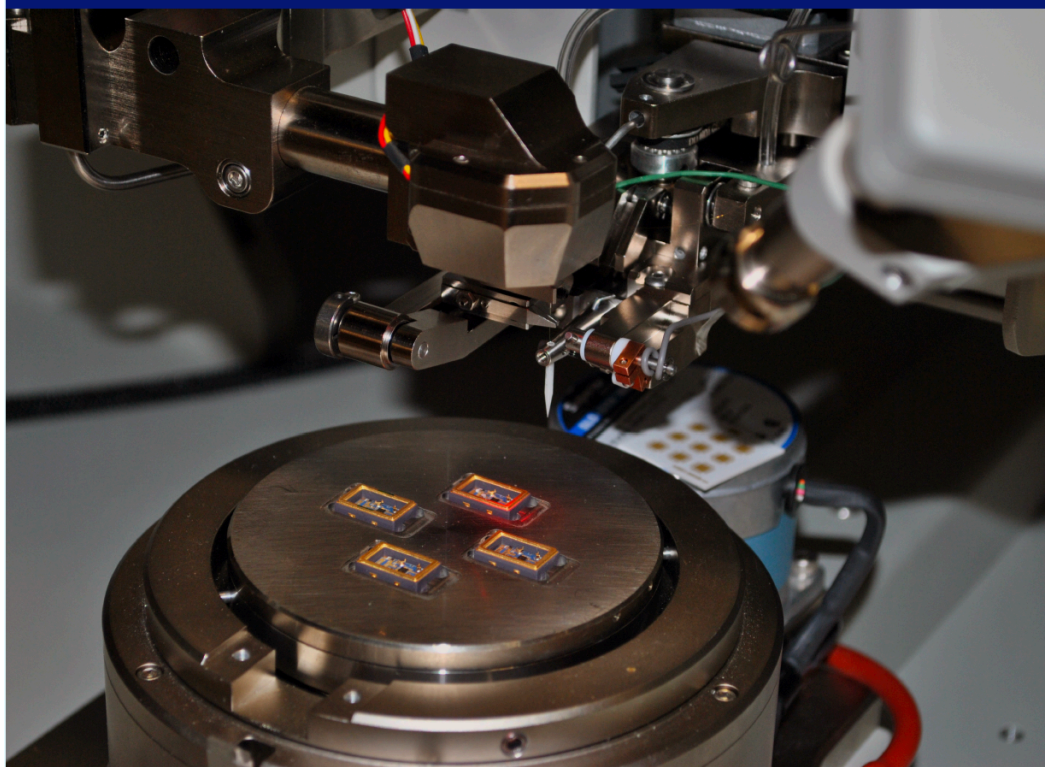
**Advanced
International
Technology**

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WWW.AITECHNOLOGY-USA.COM
858-566-2945
INFO@AITECHNOLOGY-USA.COM**



Assembly Services

**Reach up to 80 um pitch.
Video alignment system allows
placement better than 5 um
Rate up to 1 wire per second.
Ability to wire bond difficult
surfaces with manual wire bonder
at low temperatures**



Advanced International Technology

About **Advanced International Technology**

Rapid Turnaround Solutions for Dicing and Micro Assembly Services

Advanced International Technology specializes in high-quality wafer processing and dicing, micro assembly and fabrication services, providing clients with the highest degree of precision machining and engineering for the greatest possible value.

Our experts perform dicing services for a wide range of substrate materials, ranging from silicon to fused silicon, glass, ceramic and more. In addition to dicing, our innovative approaches to wire bonding allows us to complete wedge bonding, ball bonding and die bonding for customized assembly of microelectronics.

With applications in data storage, biotechnology, MEMS and nanotechnology, Advanced International Technology's engineering and manufacturing solutions assist numerous industries achieve success with exceptional products.





Advanced International Technology



Dicing Services

Wafer Dicing

Our wafer dicing service utilizes a Disco DFD 651 Automatic Dicing Saw. The dual spindle with revolutions up to 60,000 RPM allow for quick dicing reducing the time it takes to dice a wafer and ultimately cost. This machine can handle substrates up to 25 x 8" rounds at a time.

Typical substrate materials that we work with include Silicon, Quartz, Glass, Sapphire, CaF₂, and Ceramics such as Aluminum Oxide, Al₂O₃, MnO, AlN, etc. PCB's can also be cut on our machines where extreme tolerances are required. **Please have the following information available to expedite quotations:**

- » Number of streets — *Both X and Y*
- » Street size — *Our standard blades for silicon cut approximately 60 um including chipping*
- » Chipping spec — *Chipping depends on coating surface, cutting parameters and blade type*
- » Size of substrate — *Diameter and thickness*
- » Substrate Material

For more information about the superior results our dicing services can achieve, we invite you to call us at **+1 858-566-2945** or submit an inquiry via our **web form**.

On East Coast USA contact Tom Terlizzi GM SYSTEMS

WWW.GMSYSTEMS.COM terlizzi@gmsystems.com 631-269-3820



Advanced International Technology

Micro Assembly Services

Wire Bonding

We have a new process that allows us to wire bond many devices at ambient temperature. This allows gold ball wire bonding to parts that are heat sensitive such as gold plated plastic, magnetic structures, populated PCB's, etc.

Our wire bonding service utilizes a manual digital ball bonder. Bondable substrates include platinum, gold and aluminum. Copper can be bonded on a prototype and small volume basis but is not considered a permanent solution. We specialize in small batch processing and are experienced with unusual wire bonding applications.

Please include the following information when asking for a quote:

- » Number of pads
- » Size of pads and minimum pitch (measured from the center of one pad to the center of the second pad)
- » Package type
- » If bonding to a PCB, please include type of finish, size of board, and whether it is stuffed or bare.

Let's work together and grow
both our businesses together

The end